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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

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December 2015

FCP290N80

N-Channel SuperFET[®] II MOSFET 800 V, 17 A, 0.29 Ω

Features

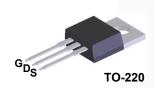
- Typ. $R_{DS(on)}$ = 0.245 Ω
- Ultra Low Gate Charge (Typ. Q_q = 58 nC)
- Low E_{oss} (Typ. 5.6 uJ @ 400 V)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 240 pF)
- · 100% Avalanche Tested
- RoHS Compliant

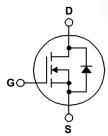
Applications

- · AC-DC Power Supply
- LED Lighting

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCP290N80	Unit
V _{DSS}	Drain to Source Voltage			800	V
.,	Cata ta Cauraa Maltaga	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f >1 Hz)	±30	
	Drain Current	- Continuous (T _C = 25°C)		17	_
ID	Drain Current	- Continuous (T _C = 100°C)		10.8	A
I _{DM}	Drain Current	- Pulsed	(Note 1)	42	Α
E _{AS}	Single Pulsed Avalanche Ene	ergy	(Note 2)	882	mJ
I _{AR}	Avalanche Current		(Note 1)	3.4	Α
E _{AR}	Repetitive Avalanche Energy	1	(Note 1)	2.12	mJ
dı /dt	MOSFET dv/dt			100	1//20
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
D	Dower Dissinction	(T _C = 25°C)		212	W
P_{D}	Power Dissipation - Dera	- Derate Above 25°C		1.7	W/°C
T _J , T _{STG}	Operating and Storage Temp	perature Range		-55 to +150	°C
T _L	Maximum Lead Temperature 1/8" from Case for 5 Seconds	o .		300	°C

Thermal Characteristics

Symbol	Parameter	FCP290N80	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.59	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	-C/VV

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Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP290N80	FCP290N80	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit		
Off Characteristics								
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	800	-	-	V		
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.8	-	V/°C		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 800 V, V _{GS} = 0 V	-	-	25			
		$V_{DS} = 640 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	250	- μ A		
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA		

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1.7 \text{ mA}$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 8.5 \text{ A}$	-	0.245	0.290	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 8.5 \text{ A}$	-	20	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	400 1/ 1/ 0 1/	-	2410	3205	pF
C _{oss}	Output Capacitance	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz	-	75	100	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	- \	0.36	-	pF
C _{oss}	Output Capacitance	V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz	- \	35	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 480 V, V _{GS} = 0 V	-	240	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 640 V, I _D = 17 A,	-	58	75	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	11	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	22	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.75	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		- /	22	54	ns
t _r		$V_{DD} = 400 \text{ V}, I_D = 17 \text{ A},$	- /	14	38	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	-	61	132	ns
t _f	Turn-Off Fall Time	(Note 4)	/-	2.6	15	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diod	Maximum Continuous Drain to Source Diode Forward Current		-	17	Α
I_{SM}	Maximum Pulsed Drain to Source Diode Fo	Maximum Pulsed Drain to Source Diode Forward Current			42	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 17 A	-		1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 17 A,	-	511	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	12	-	μС

Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I_{AS} = 3.4 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C.
- 3. $I_{SD} \le$ 17 A, di/dt \le 200 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

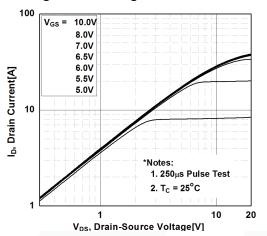


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

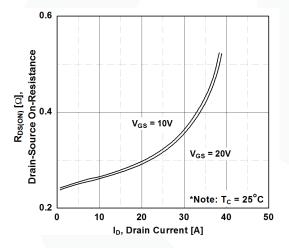


Figure 5. Capacitance Characteristics

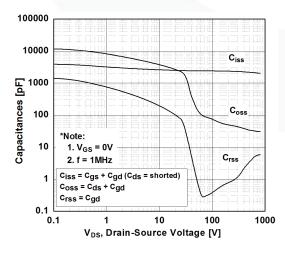


Figure 2. Transfer Characteristics

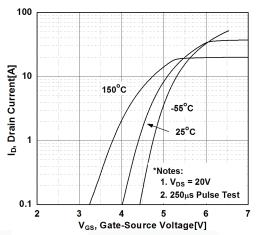


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

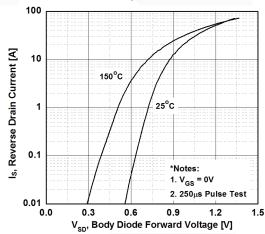
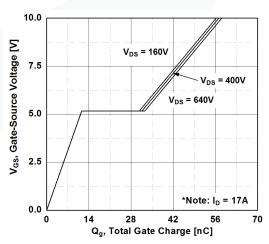


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

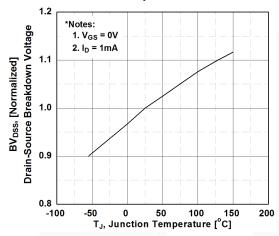


Figure 9. Maximum Safe Operating Area

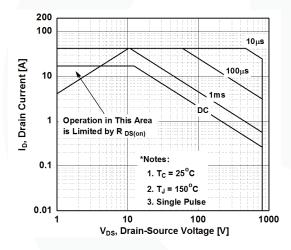


Figure 11. Eoss vs. Drain to Source Voltage

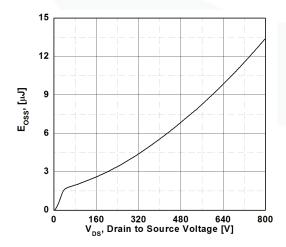


Figure 8. On-Resistance Variation vs. Temperature

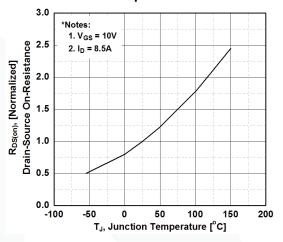
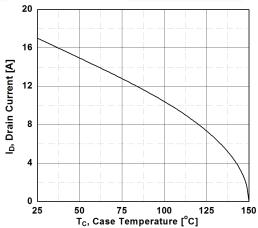


Figure 10. Maximum Drain Current vs. Case Temperature

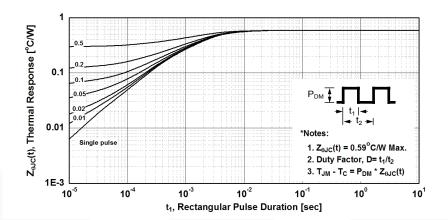


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Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



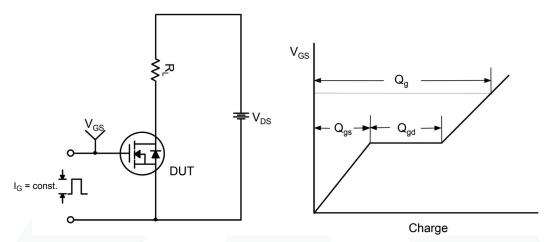


Figure 13. Gate Charge Test Circuit & Waveform

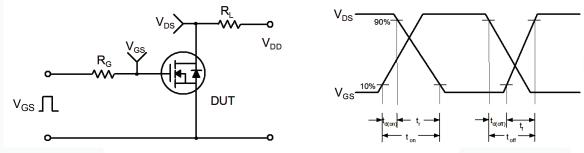


Figure 14. Resistive Switching Test Circuit & Waveforms

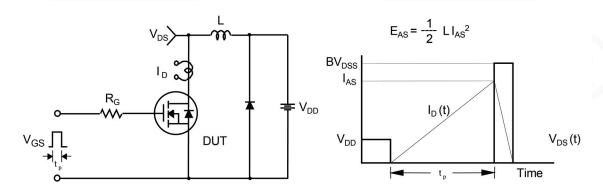


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

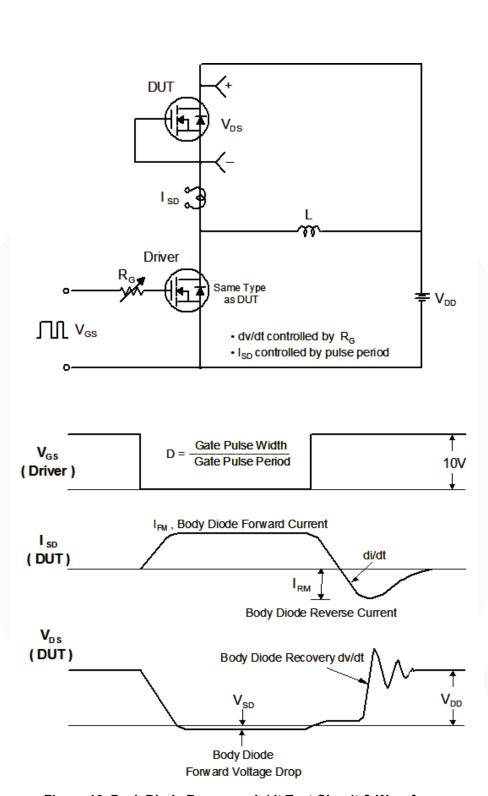
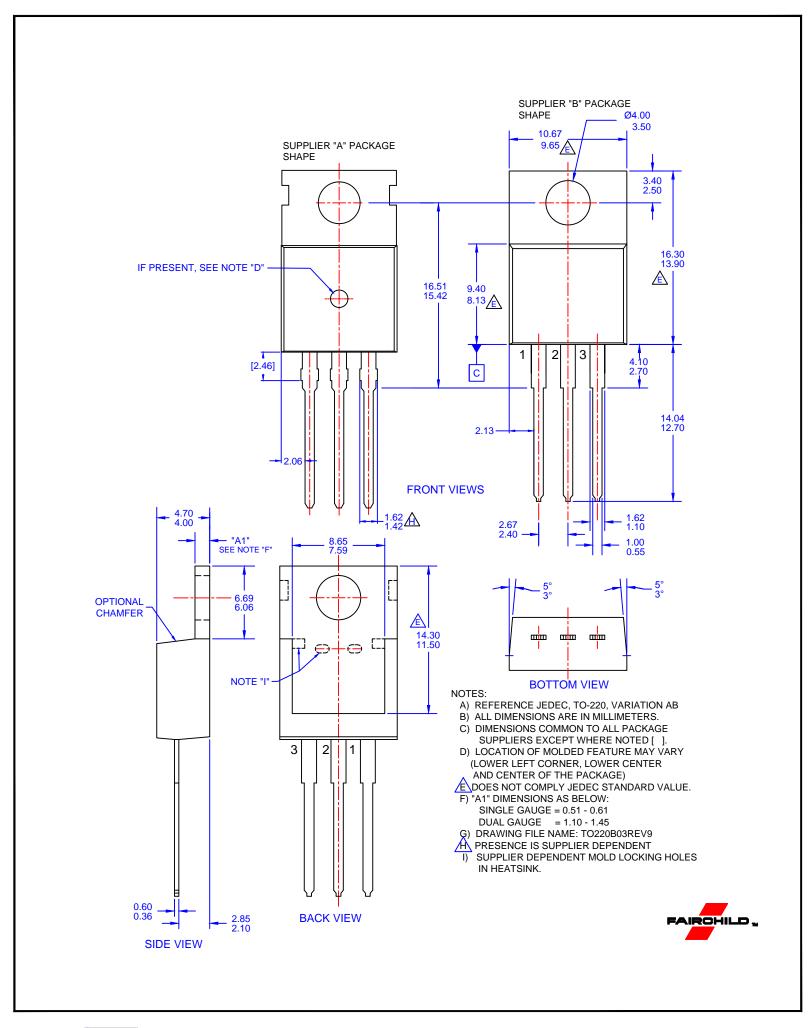


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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